



Micro Commercial Components

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20736 Marilla Street Chatsworth
CA 91311
Phone: (818) 701-4933
Fax: (818) 701-4939

LLSD101A THRU LLSD101C

Features

- Guard Ring Construction for Transient Protection
- Low Reverse Capacitance
- Low Forward Voltage Drop and Low Reverse Recovery Time
- Lead Free Finish/RoHS Compliant(Note 1) ("P" Suffix designates Compliant. See ordering information)

Mechanical Data

- Case: MiniMELF, Glass
- Terminals: Solderable per MIL-STD-202, Method 208
- Polarity: Indicated by Cathode Band
- Weight: 0.05 grams (approx.)

Maximum Ratings @ 25°C Unless Otherwise Specified

Characteristic	Symbol	LLSD101A	LLSD101B	LLSD101C
Peak Repetitive Reverse Voltage	V_{RRM}			
Working Peak Reverse Voltage	V_{RWM}	60V	50V	40V
DC Blocking Voltage	V_R			
RMS Reverse Voltage	$V_{R(RMS)}$	42V	35V	28V
Forward Continuous Current(Note 2)	I_{FM}	15mA		
Non-Repetitive Peak @ $t \leq 1.0s$ Forward Surge Current @ $t = 10\mu s$	I_{FSM}	50mA 2.0A		
Power Dissipation(Note 2)	P_d	400mW		
Thermal Resistance(Note 2)	R	375K/W		
Operation & Storage Temp. Range	T_j, T_{STG}	-55 to 150°C		

Electrical Characteristics @ 25°C Unless Otherwise Specified

Characteristic	Symbol	Min	Max	Unit	Test Cond.
Peak Reverse Current	I_{RM}	-----	200	nA	$V_R = 50V$ $V_R = 40V$ $V_R = 30V$
Forward Volt. Drop	V_{FM}	-----	0.41 0.40 0.39 1.00 0.95 0.90	V	$I_F = 1.0mA$ $I_F = 1.0mA$ $I_F = 1.0mA$ $I_F = 15mA$ $I_F = 15mA$ $I_F = 15mA$
Junction Capacitance	C_j	-----	2.0 2.1 2.2	pF	$V_R = 0V, f = 1.0MHz$
Reverse Recovery Time	t_{rr}	-----	1.0	ns	$I_F = I_R = 5mA,$ recover to 0.1 I_R

Note:1.Lead in Glass Exemption Applied, see EU Directive Annex 5.
2.Valid provided that electrodes are kept at ambient temperature

Schottky Barrier Switching Diode

MINIMELF

The diagram shows a side view of a MiniMELF diode. Dimension A is the total length, B is the width of the body, and C is the height. A shaded vertical band on the top surface is labeled 'Cathode Mark'.

DIM	DIMENSION				NOTE
	INCHES		MM		
	MIN	MAX	MIN	MAX	
A	.134	.142	3.40	3.60	
B	.008	.016	.20	.40	
C	.055	.059	1.40	1.50	

SUGGESTED SOLDER PAD LAYOUT

The diagram shows two rectangular solder pads. The distance between the centers of the pads is 0.105 inches. The height of each pad is 0.075 inches. The width of each pad is 0.030 inches.

LLSD101A thru LLSD101C

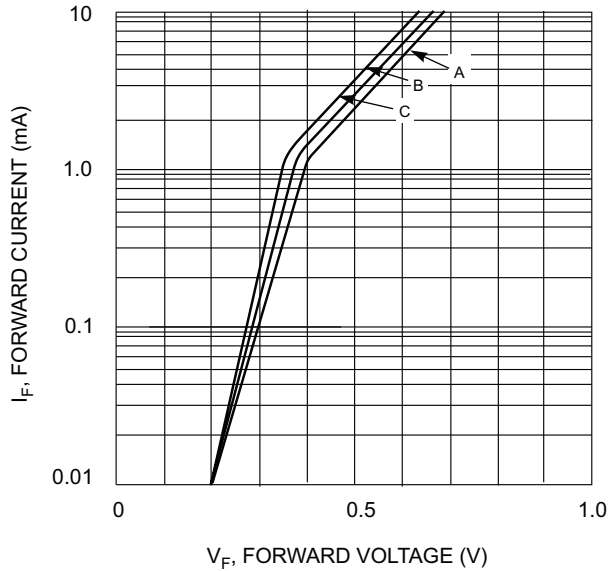


Fig. 1 Typical Forward Characteristic Variations for Primary Conduction

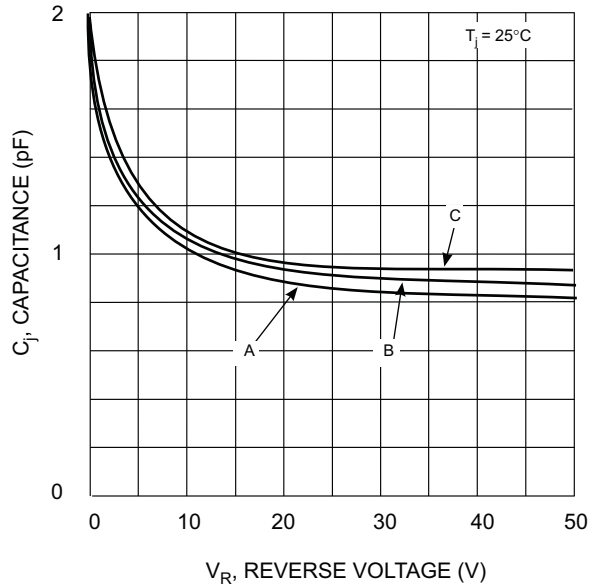


Fig. 2 Typ. Junction Capacitance vs Reverse Voltage



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Ordering Information

Device (Part Number)-TP	Packing Tape&Reel;2.5Kpcs/Reel
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